

REMARKS

At the outset, the Examiner is thanked for the thorough review and consideration of the pending application. The final Office Action dated July 17, 2006, has been received and its contents carefully reviewed.

Claims 8-14 are withdrawn in this application. Claims 1-6 and 15-20 are rejected to by the Examiner. Claims 1 and 15 have been amended. No new matter has been added. Claims 1-6 and 8-20 remain pending in this application.

In the Office Action, claims 1-6 and 15-20 are rejected under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent No. 6,259,119 to Ahn et al. (hereinafter "Ahn").

The rejection of claims 1-6 and 15-20 is respectfully traversed and reconsideration is requested. Claims 1-6 are allowable over the cited references in that each of these claims recites a combination of elements including, for example, "a heat generated alloy layer on the entire surface of the first metal layer by heat generated by depositing a second metal on the first metal layer." Claims 15-20 are allowable over the cited references in that each of these claims recites a combination of elements including, for example, "wherein the gate electrode and gate pad both include a first layer formed of a first metal and a second layer formed of a heat generated alloy formed on the entire surface of the first layer by heat generated by depositing a second metal on the first metal, the second metal is removed so that the heat generated alloy is exposed to the entire surface of a first metal layer and directly connected to the transparent electrode." Ahn does not teach or suggest at least this feature of the claimed invention.

The present invention has a heat generated alloy layer formed on the entire surface of the first metal layer. In Ahn the intermetallic layer 199 is formed in a region between the low resistance gate pad 117a and a second metal gate pad 117 as shown in Fig. 7a. Therefore, Ahn does not teach "a second layer formed of a heat generated alloy formed on the entire surface of the first layer." Accordingly, Applicant respectfully submits that claims 1-6 and 15-20 are allowable over the cited references.

Applicants believe the foregoing amendments place the application in condition for allowance and early, favorable action is respectfully solicited.

If for any reason the Examiner finds the application other than in condition for allowance, the Examiner is requested to call the undersigned attorney at (202) 496-7500 to discuss the steps necessary for placing the application in condition for allowance. All correspondence should continue to be sent to the below-listed address.

If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. § 1.136, and any additional fees required under 37 C.F.R. § 1.136 for any necessary extension of time, or any other fees required to complete the filing of this response, may be charged to Deposit Account No. 50-0911. Please credit any overpayment to deposit Account No. 50-0911. *A duplicate copy of this sheet is enclosed.*

Respectfully submitted,

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By


Eric J. Nuss

Registration No. 40,106
McKENNA LONG & ALDRIDGE LLP
1900 K Street, N.W.
Washington, DC 20006
(202) 496-7500
Attorneys for Applicant